TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSIII)

## 2SK3017

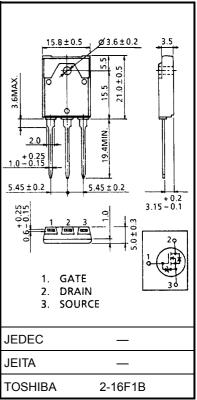
# DC-DC Converter, Relay Drive and Motor Drive Applications

Unit: mm

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : R_{DS}\ (ON) = 1.05\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 7.0\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 720\ V) \\ \bullet & Enhancement-mode & : V_{th} = 2.0 \sim 4.0\ V\ (V_{DS} = 10\ V,\ I_{D} = 1\ mA) \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	900	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	900	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	8.5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	25.5	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	90	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	966	mJ	
Avalanche current		I <sub>AR</sub>	8.5	Α	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	9	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	



Weight: 5.8 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.39	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	41.6	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 24.5 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 8.5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

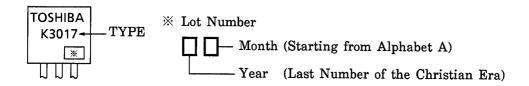
### **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V		_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 720 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	900	_	_	V
Gate threshold v	/oltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A	_	1.05	1.25	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4 A	3.5	7.0	_	S
Input capacitano	ce	C <sub>iss</sub>		_	2150	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	35	_	pF
Output capacitance		Coss			220	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{\circ} V_{OUT}$ $V_{GS} \stackrel{10 \text{ V}}{\circ} V_{OUT}$ $R_{L} = 100 \Omega$ $V_{DD} = 400 \text{ V}$	_	25	_	
	Turn-on time	t <sub>on</sub>		ı	60	1	ns
	Fall time	t <sub>f</sub>		_	25	_	i lis
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm w} = 10 \mu{\rm s}$	_	120	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	70	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		37		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			33	_	

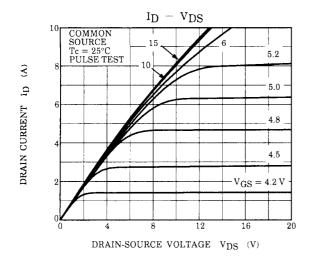
### Source-Drain Ratings and Characteristics (Ta = 25°C)

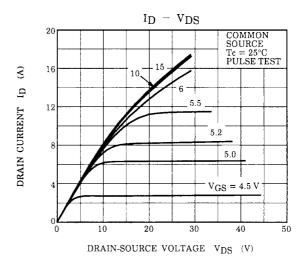
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>		_		8.5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	25.5	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 8.5 A, V <sub>GS</sub> = 0 V	_	_	-1.9	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 8.5 A, V <sub>GS</sub> = 0 V	_	1300	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 100 Å / μs	_	14.5		μC

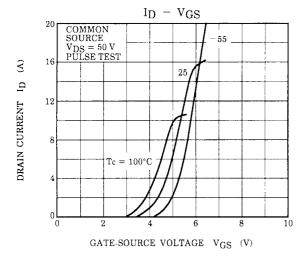
## Marking

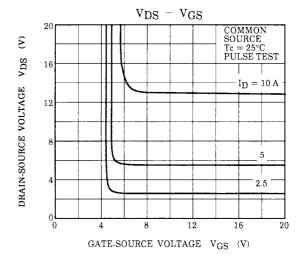


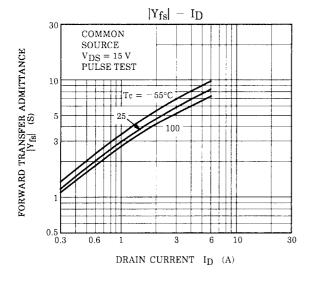
2 2002-07-31

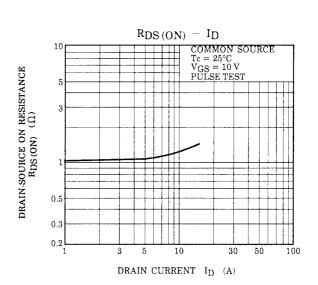




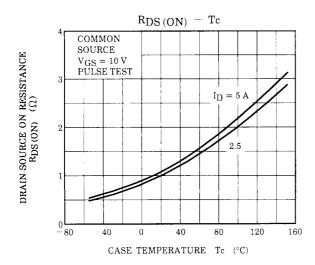


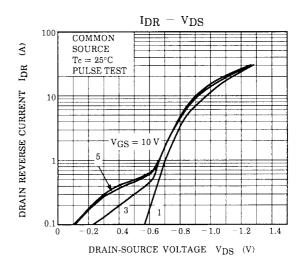


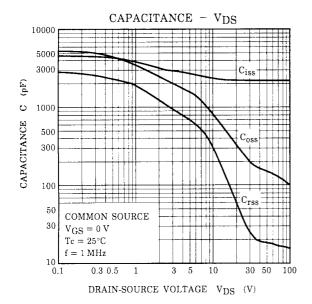


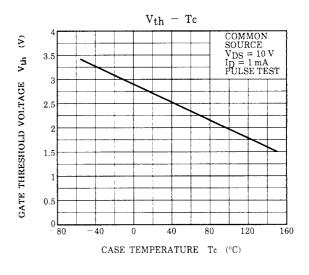


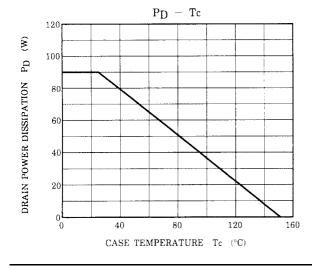
3

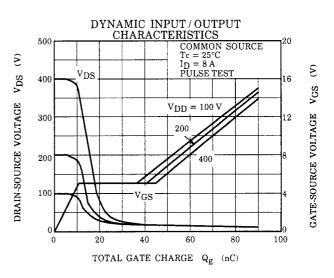




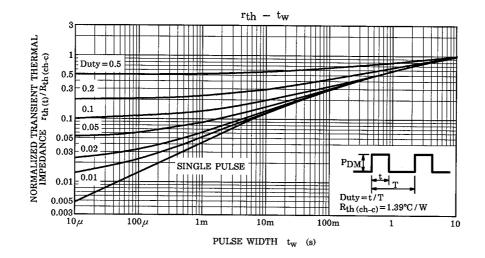


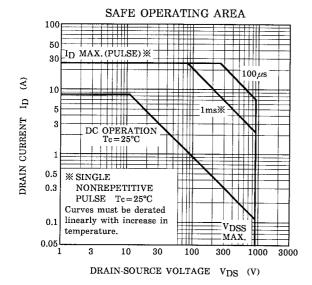


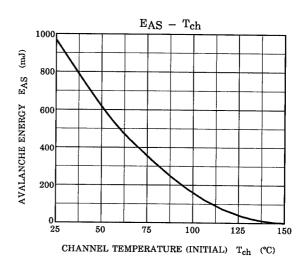


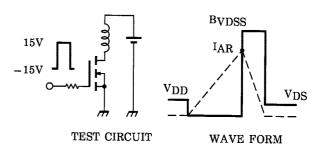


4









$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 24.5~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

#### **RESTRICTIONS ON PRODUCT USE**

000707EAA

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The information contained herein is presented only as a guide for the applications of our products. No
  responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other
  rights of the third parties which may result from its use. No license is granted by implication or otherwise under
  any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.